- For Application as a"Scratch Pad" Memory with Nondestructive Read-Out
- Fully Decoded Memory Organized as 16 Words of Four Bits Each
- Fast Access Time . . . 33 ns Typical
- Diode-Clamped, Buffered Inputs
- Open-Collector Outputs Provide Wire-AND Capability
- Typical Power Dissipation . . . 375 mW
- Compatible with Most TTL Circuits

description

This 64-bit active-element memory is a monolithic, high-speed, transistor-transistor logic (TTL) array of 64 flip-flop memory cells organized in a matrix to provide 16 words of four bits each. Each of the 16 words is addressed in straight binary with full on-chip decoding.

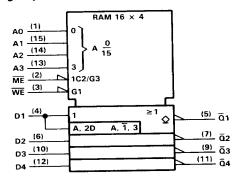
The buffered memory inputs consist of four address lines, four data inputs, a write enable, and a memory enable for controlling the entry and access of data. The memory has open-collector outputs which may be wired-AND connected to permit expansion up to 4704 words of N-bit length without additional output buffering. Access time is typically 33 nanoseconds; power dissipation is typically 375 milliwatts.

FUNCTION TABLE

ME	WE	OPERATION	CONDITION OF OUTPUTS			
	L	Write	Complement of Data Inputs			
L	н	Read	Complement of Selected Word			
Н	L	Inhibit Storage	Complement of Data Inputs			
н	Н	Do Nothing	High			

SN7489 . . . J OR N PACKAGE (TOP VIEW) ао П₁ U16∏ VCC ME □2 15 A1 WE 3 14 A2 D1 🛮 4 13 🛮 A3 12 D4 ₫1 🛮 5 11 🔲 Q̄4 D2 🛮 6 10 D3 Q2 7 GND 8 9∏ <u>ā</u>3

logic symbol



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AMs

write operation

Information present at the data inputs is written into the memory by addressing the desired word and holding both the memory enable and write enable low. Since the internal output of the data input gate is common to the input of the sense amplifier, the sense output will assume the opposite state of the information at the data inputs when the write enable is low.

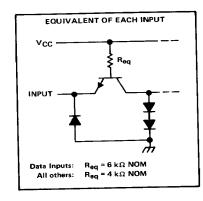
read operation

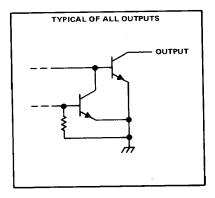
The complement of the information which has been written into the memory is nondestructively read out at the four sense outputs. This is accomplished by holding the memory enable low, the write enable high, and selecting the desired address.

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D4 (12)

schematics of inputs and outputs





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	<i></i>
Input voltage (see Note 1)	5.5 V
Input voltage (see Note 1)	5.5 V
High-level output voltage, VOH (see Notes 1 and 2/	0°C to 70°C
Operating free-air temperature range	65 °C +0 150 °C
Storage temperature range	= 65°C 10 150 C

NOTES: 1. Voltage values are with respect to network ground terminal.

2. This is the maximum voltage that should be applied to any output when it is in the off state.

recommended operating conditions

	MIN	NOM	MAX	UNIT
A CONTRACTOR OF THE CONTRACTOR	4.75	5	5.25	V
Supply voltage, VCC	40			ns
Width of write-enable pulse, tw	40			ns
Setup time, data input with respect to write enable, t _{su} (see Figure 1)				ns
Hold time, data input with respect to write enable, th (see Figure 1)	5			
Select input setup time with respect to write enable, t _{SU}	0			ns
Select input hold time after writing, th (see Figure 1)	5			ns
	0		70	°C
Operating free-air temperature, TA				

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3AMs

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

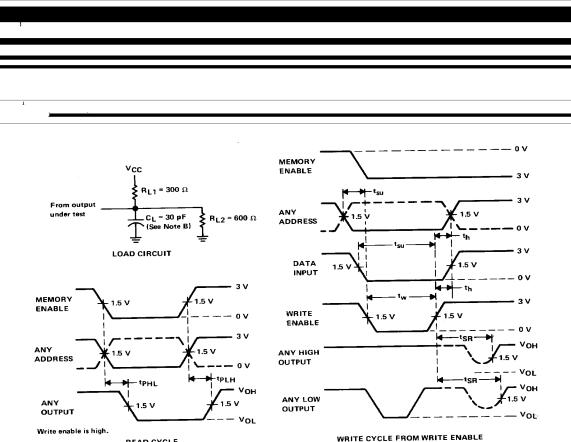
	PARAMETER	TEST CONDITIONS†		MIN TYP	MAX	UNIT
V_{IH}	High-level input voltage			2		V
VIL	Low-level input voltage				0.8	v
ViK	Input clamp voltage	VCC = MIN,	$l_i = -12 \text{ mA}$		- 1.5	v
ЮН	High-level output current	V _{CC} = MIN, V _{IL} = 0.8 V,	$V_{IH} = 2 V$, $V_{OH} = 5.5 V$		20	μА
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH}	= 2 V, 1 _{OL} = 12 mA 1 _{OL} = 16 mA		0.4	V
lj.	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 5.5 V		1	mA
ΊΗ	High-level input current	V _{CC} = MAX,	V _f = 2.4 V		40	μА
l _I L	Low-level input current	V _{CC} = MAX,	V _I = 0.4 V		-1.6	mA
Icc	Supply current	V _{CC} = MAX,	See Note 3	75		mA
Со	Off-state output capacitance	V _{CC} = 5 V, f = 1 MHz	V _O = 2.4 V,	6.5		pF

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, output from memory er			26		50	
^t PHL	Propagation delay time, output from memory en	•	$C_L = 30 \text{ pF},$		33	50	ns
^t PLH	Propagation delay time, low-to-high-level output from any address input		$R_{L1} = 300 \Omega$, $R_{L2} = 600 \Omega$, See Figure 1	30 60		60	
^t PHL	Propagation delay time, high-to-low-level output from any address input				35	60	ns
*	Sense recovery time Output initially high				39	70	
tSR	after writing	Output initially low			48	70	ns

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. NOTE 3: I_{CC} is measured with the memory enable grounded, all other inputs at 4.5 V, and all outputs open.



NOTES: A. The input pulse generators have the following characteristics: $t_f \le 10$ ns, $t_f \le 10$ ns, PRR = 1 MHz, $Z_{out} \approx 50 \ \Omega$. B. C_L includes probe and jig capacitance.

READ CYCLE

FIGURE 1-SWITCHING CHARACTERISTICS

TYPICAL CHARACTERISTICS

